

Four Output Low Power Differential Fanout Buffer for PCI Express Gen1, Gen2, and QPI

9DBL411B

Recommended Application:

PCI-Express Gen2 or QPI fanout buffer

Output Features:

- 4 low power differential output pairs
- Individual OE# control of each output pair

Key Specifications:

- Output cycle-cycle jitter < 15ps additive
- Output to output skew: < 50ps

Features/Benefits:

- Low power differential outputs for PCI-Express and QPI clocks
- Power down mode when all OE# are high
- Available in I-temp
- 20-pin MLF or TSSOP packaging

General Description:

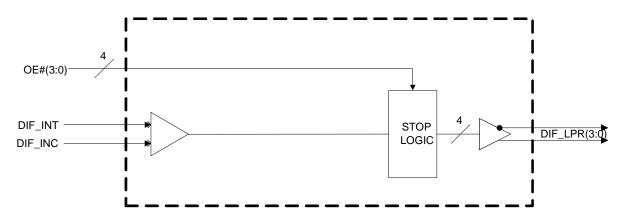
The **9DBL411B** is a 4 output lower power differential buffer. Each output has its own OE# pin. It has a maximum operating frequency of 150 MHz.

Power Groups

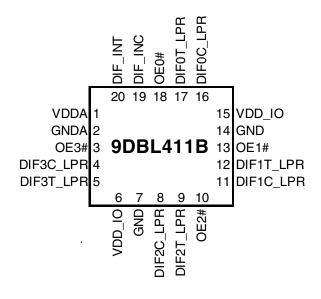
Pin Numl	per (TSSOP)	Description
VDD	GND	Description
9,18	10,17	VDD_IO for DIF(3:0)
4	5	3.3V Analog VDD & GND

Pin Number (MLF)		- Description	
VDD	GND	Description	
6,15	7,14	VDD_IO for DIF(3:0)	
1	2	3.3V Analog VDD & GND	

Functional Block Diagram



Pin Configurations

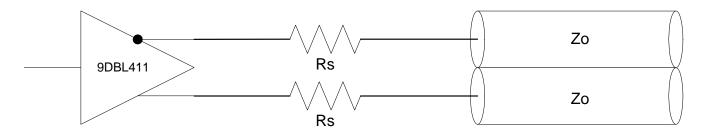


DIF_INC 2 19 DIF0C_LPR DIF_INT 3 18 VDD_IO VDDA 4 17 GND GNDA 5 16 OE1# OE3# 6 15 DIF1T_LPR DIF3C_LPR 7 14 DIF1C_LPR DIF3T_LPR 8 6 13 OE2#
VDDA 4 17 GND GNDA 5 16 OE1# OE3# 6 15 DIF1T_LPR DIF3C_LPR 7 14 DIF1C_LPR
OE3# 6 15 DIF1T_LPR DIF3C_LPR 7 14 DIF1C_LPR
OE3# 6 15 DIF1T_LPR DIF3C_LPR 7 14 DIF1C_LPR
DIF3C_LPR 7
DIF3C_LPR 7 14 DIF1C_LPR
VDD_IO 9 12 DIF2T_LPR
GND 10 11 DIF2C_LPR

20-pin MLF

20-pin TSSOP

Terminations



Zo-17=Rs (ohms), where Zo is the single-ended intrinsic impedance of the board transmission line. Single-ended intrinsic impedance is $\frac{1}{2}$ that of the differential impedance.

Single Ended	Rs		
Impedance	5%	Rs	
(Zo)	tolerance	2% tolerance	Notes
50	33	33.2	In general, 5% resistors
45	27	27.4	may be used. All values are
42.5	24 or 27	24.9	in ohms.

IDT® Four Output Low Power Differential Buffer for PCI Express for Gen1, Gen2, and QPI

TSSOP Pin Description

PIN # (TSSOP)	PIN NAME	PIN TYPE	DESCRIPTION	
-1	OE0#	IN	Output Enable for DIF0 output. Control is as follows:	
	OE0#	IIN	0 = enabled, 1 = Low-Low	
2	DIF_INC	IN	Complement side of differential input clock	
3	DIF_INT	IN	True side of differential input clock	
4	VDDA	PWR	3.3V Power for the Analog Core	
5	GNDA	GND	Ground for the Analog Core	
6	OE3#	IN	Output Enable for DIF3 output. Control is as follows:	
0	OL3#	IIN	0 = enabled, 1 = Low-Low	
7	DIF3C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)	
8	DIF3T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)	
9	VDD_IO	PWR	Power supply for low power differential outputs, nominal 1.05V to 3.3V	
10	GND	GND	Ground pin	
11	DIF2C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)	
12	DIF2T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)	
13	OE2#	IN	Output Enable for DIF2 output. Control is as follows:	
13	OE2#	IIN	0 = enabled, 1 = Low-Low	
14	DIF1C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)	
15	DIF1T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)	
16	16 OE1# IN		Output Enable for DIF1 output. Control is as follows:	
16 OE1# IN		IIN	0 = enabled, 1 = Low-Low	
17	GND	GND	Ground pin	
18	VDD_IO	PWR	Power supply for low power differential outputs, nominal 1.05V to 3.3V	
19	DIF0C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)	
20	DIF0T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)	

MLF Pin Description

PIN # (MLF)	PIN NAME	PIN TYPE	DESCRIPTION		
1	VDDA	PWR	3.3V Power for the Analog Core		
2	GNDA	GND	Ground for the Analog Core		
3	OE3#	IN	Output Enable for DIF3 output. Control is as follows: 0 = enabled, 1 = Low-Low		
4	DIF3C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)		
5	DIF3T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)		
6	VDD_IO	PWR	Power supply for low power differential outputs, nominal 1.05V to 3.3V		
7	GND	GND	Ground pin		
8	DIF2C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)		
9	DIF2T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)		
10	OE2#	IN	Output Enable for DIF2 output. Control is as follows: 0 = enabled, 1 = Low-Low		
11	DIF1C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)		
12	DIF1T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)		
13	OE1#	IN	Output Enable for DIF1 output. Control is as follows: 0 = enabled, 1 = Low-Low		
14	GND	GND	Ground pin		
15	VDD_IO	PWR	Power supply for low power differential outputs, nominal 1.05V to 3.3V		
16	DIF0C_LPR	OUT	Complement clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)		
17	DIF0T_LPR	OUT	True clock of low power differential clock pair. (no 50ohm shunt resistor to GND needed)		
18	OE0#	IN	Output Enable for DIF0 output. Control is as follows: 0 = enabled, 1 = Low-Low		
19	DIF_INC	IN	Complement side of differential input clock		
20	DIF_INT	IN	True side of differential input clock		

Absolute Maximum Ratings

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	Notes
Maximum Supply Voltage	VDDA	Core Supply Voltage		4.6	V	1,7
Maximum Supply Voltage	VDD_IO	Low-Voltage Differential I/O Supply	0.99	3.8	V	1,7
Maximum Input Voltage	V _{IH}	3.3V LVCMOS Inputs		4.6	V	1,7,8
Minimum Input Voltage	V _{IL}	Any Input	Vss - 0.5		٧	1,7
Ambient Operating Temp	TambCOM	Commercial Range	0	70	°C	1
Ambient Operating Femp	TambIND	Industrial Range	-40	85	°C	1
Storage Temperature	Ts	-	-65	150	°C	1,7
Input ESD protection	ESD prot	Human Body Model	2000		V	1,7

Electrical Characteristics - Input/Supply/Common Output Parameters

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	Notes
Supply Voltage	VDDxxx	Supply Voltage	3.000	3.600	V	1
Supply Voltage	VDDxxx_IO	Low-Voltage Differential I/O Supply	0.99	3.600	V	1
Input High Voltage	V _{IHSE}	Single-ended inputs	2	$V_{DD} + 0.3$	V	1
Input Low Voltage	V_{ILSE}	Single-ended inputs	V _{SS} - 0.3	0.8	٧	1
Differential Input High Voltage	V _{IHDIF}	Differential inputs (single-ended measurement)	600	1.15	V	1
Differential Input Low Voltage	V_{ILDIF}	Differential inputs (single-ended measurement)	V _{SS} - 0.3	300	٧	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4	8	V/ns	2
Input Leakage Current	I _{IN}	$V_{IN} = V_{DD}, V_{IN} = GND$	-5	5	uA	1
Operating Supply Current	I _{DD_3.3V}	VDDA supply current		20	mA	1
Operating Supply Surrent	I _{DD_IO_133M}	VDD_IO supply @ fOP = 133MHz		20	mA	1
Power Down Current	I _{DD_SB_3.3V}	VDDA supply current, Input stopped, OE# pins all high		750	uA	1
(All OE# pins High)	I _{DD_SBIO}	VDD_IO supply, Input stopped, OE# pins all high		150	uA	1
Input Frequency	F _i	$V_{DD} = 3.3 \text{ V}$	15	150	MHz	2
Pin Inductance	L_{pin}			7	nΗ	1
Input Capacitance	C_{IN}	Logic Inputs	1.5	5	pF	1
три Оараскансе	C _{OUT}	Output pin capacitance		6	pF	1
OE# latency (at least one OE# is low)	$T_{OE\#LAT}$	Number of clocks to enable or disable output from assertion/deassertion of OE#	1	3	periods	1
Clock stabilization time (from all OE# high to first OE# low).	T _{STAB}	Delay from assertion of first OE# to first clock out (assumes input clock running)		150	ns	1
Tdrive_OE#	T _{DROE#}	Output enable after OE# de-assertion		10	ns	1
Tfall_OE#	T_{FALL}	Fall/rise time of OE# inputs		5	ns	1
Trise_OE#	T_{RISE}	. am noo am on o z mapato		5	ns	1

AC Electrical Characteristics - DIF Low Power Differential Outputs

PARAMETER	SYMBOL	CONDITIONS	MIN	MAX	UNITS	NOTES
Rising Edge Slew Rate	t _{slR}	Differential Measurement	1.5	4	V/ns	1,2
Falling Edge Slew Rate	t _{FLR}	Differential Measurement	1.5	4	V/ns	1,2
Slew Rate Variation	t _{slvar}	Single-ended Measurement		20	%	1
Maximum Output Voltage	V_{HIGH}	Includes overshoot		1150	mV	1
Minimum Output Voltage	V_{LOW}	Includes undershoot	-300		mV	1
Differential Voltage Swing	V _{SWING}	Differential Measurement	1200		mV	1
Crossing Point Voltage	V _{XABS}	Single-ended Measurement	300	550	mV	1,3,4
Crossing Point Variation	V _{XABSVAR}	Single-ended Measurement		140	mV	1,3,5
Duty Cycle Distortion	D _{CYCDIS0}	Differential Measurement, fIN<=133.33MHz		3	%	1,6
Additive Cycle to Cycle Jitter	DIFJ _{C2CADD}	Differential Measurement, Additive		15	ps	1
DIF[3:0] Skew	DIF _{SKEW}	Differential Measurement		50	ps	1
Propagation Delay	t _{PD}	Input to output Delay	2.5	3.5	ns	1
Additive Phase Jitter - PCIe Gen1	t phase_addPClG1	1.5MHz < 22MHz		6	ps Pk-Pk	1,9
Additive Phase Jitter - PCIe Gen2 High Band	t _{phase_addPClG2Hl}	High Band is 1.5MHz to Nyquist (50MHz)		0.16	ps rms	1,9
Additive Phase Jitter PCle Gen2 Low Band	t _{phase_addPCIG2LO}	Low Band is 10KHz to 1.5MHz		0.07	ps rms	1,9
Additive Phase Jitter QPI133 (6.4GBs, 12 UI)	t _{phase_addQPI6G4}	11MHz to 33MHz		0.04	ps rms	1,9

Notes on Electrical Characteristics (all measurements use 9LRS3187B as clock source and R_S=33ohms/C_L=2pF test load):

¹Guaranteed by design and characterization, not 100% tested in production.

² Slew rate measured through Vswing centered around differential zero

³ Vxabs is defined as the voltage where CLK = CLK#

⁴ Only applies to the differential rising edge (CLK rising and CLK# falling)

⁵ Defined as the total variation of all crossing voltages of CLK rising and CLK# falling. Matching applies to rising edge rate of CLK and falling edge of CLK#. It is measured using a +/-75mV window centered on the average cross point where CLK meets CLK#.

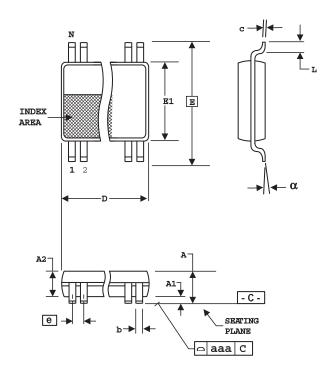
⁶ This figure refers to the maximum distortion of the input wave form.

⁷ Operation under these conditions is neither implied, nor guaranteed.

⁸ Maximum input voltage is not to exceed maximum VDD

⁹ The 9DBL411B has no PLL, so the part itself contributes very little jitter to the input clock. But this also means that the 9DBL411 cannot 'de-jitter' a noisy input clock. Values calculated per PCI SIG and per Intel Clock Jitter tool version 1.5

20-pin TSSOP Package Drawing and Dimensions



20-Lead, 4.40 mm. Body, 0.65 mm. Pitch TSSOP (173 mil) (25.6 mil)

	(17	3 IIIII <i>)</i>	(25.6 11111)		
	In Milli	meters	In Inches		
SYMBOL	COMMON D	IMENSIONS	COMMON DIMENSIONS		
	MIN	MAX	MIN	MAX	
Α		1.20		.047	
A1	0.05	0.15	.002	.006	
A2	0.80	1.05	.032	.041	
b	0.19	0.30	.007	.012	
С	0.09	0.20	.0035	.008	
D	SEE VAF	SEE VARIATIONS		SEE VARIATIONS	
E	6.40 E	BASIC	0.252 BASIC		
E1	4.30	4.50	.169	.177	
е	0.65 BASIC		0.0256 BASIC		
L	0.45	0.75	.018	.030	
N	SEE VARIATIONS		SEE VAF	RIATIONS	
а	0°	8°	0°	8°	
aaa		0.10		.004	

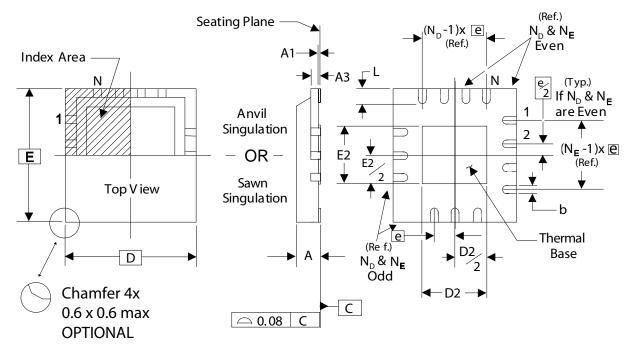
VARIATIONS

N	D n	nm.	D (inch)	
IN	MIN	MAX	MIN	MAX
20	6.40	6.60	.252	.260

Reference Doc.: JEDEC Publication 95, MO-153

10-0035

20-pin MLF Package Drawing and Dimensions



THERMALLY ENHANCED, VERY THIN, FINE PITCH QUAD FLAT / NO LEAD PLASTIC PACKAGE

DIMENSIONS

SYMBOL	MIN.	MAX.	
Α	0.8	1.0	
A1	0	0.05	
A3	0.20 Reference		
b	0.18	0.3	
е	0.50 BASIC		

DIMENSIONS

SYMBOL	ICS 20L TOLERANCE	
N	20	
N_D	5	
N _E	5	
D x E BASIC	4.00 x 4.00	
D2 MIN. / MAX.	2.00 / 2.25	
E2 MIN. / MAX.	2.00 / 2.25	
L MIN. / MAX.	0.45 / 0.65	

Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
9DBL411BKLF	Tubes	20-pin MLF	0 to +70°C
9DBL411BKLFT	Tape and Reel	20-pin MLF	0 to +70°C
9DBL411BGLF	Tubes	20-pin TSSOP	0 to +70°C
9DBL411BGLFT	Tape and Reel	20-pin TSSOP	0 to +70°C
9DBL411BKILF	Tubes	20-pin MLF	-40 to +85°C
9DBL411BKILFT	Tape and Reel	20-pin MLF	-40 to +85°C
9DBL411BGILF	Tubes	20-pin TSSOP	-40 to +85°C
9DBL411BGILFT	Tape and Reel	20-pin TSSOP	-40 to +85°C

[&]quot;LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

[&]quot;B" is the device revision designator (will not correlate to the datasheet revision).

Revision History

Rev.	Issue Date	Description	Page #
0.1 1/8/20		Initial Release. Compared with A rev the following have changed:	
	1/9/2010	1. Added I-temp version	
		2. Updated electrical tables for I-temp	
		3. Revised Phase Jitter specs and added QPI.	
Α	1/8/2010	Released to final.	
В	4/23/2010	Changed Input Frequency from 33 min to 15 MHz min	5
С	10/18/2010	Updated Supply Voltage min/max ratings.	5

This product is protected by United States Patent NO. 7, 342, 420 and other patents.

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